CY54FCT646T . . . D PACKAGE

CY74FCT646T . . . Q OR SO PACKAGE

(TOP VIEW)

1

CPAB [

SAB 🛙 2

DIR 🛛 3

A<sub>1</sub> 4

A<sub>2</sub> 5

A3 6

A<sub>5</sub> 8

A<sub>6</sub> 🛛 9

A7 [ 10

A<sub>8</sub> 11

DIR SAB

 $A_1$ 

 $A_2$ 6 3

12

CPAB

CY54FCT646T ... L PACKAGE

(TOP VIEW)

N N N N

2 1 28 27

GND

A₄ 7

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24 Vcc

22 SBA

21 🛛 G

20 B1

19 B<sub>2</sub>

18 B<sub>3</sub>

17 🛛 B<sub>4</sub>

16 B<sub>5</sub>

15 B<sub>6</sub>

14 🛛 B<sub>7</sub>

13 🛛 B<sub>8</sub>

CPBA

N m h m

SBA

G

B<sub>2</sub>

NC Г

B<sub>3</sub>

 $B_4$ 

Г  $B_5$ 

24 B<sub>1</sub>

23 🛛 CPBA

- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V<sub>OH</sub> (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise **Characteristics**
- Ioff Supports Partial-Power-Down Mode • Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and **Output Logic Levels**
- ESD Protection Exceeds JESD 22 - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Independent Register for A and B Buses
- **CY54FCT646T** 
  - 48-mA Output Sink Current
  - 12-mA Output Source Current
- CY74FCT646T
  - 64-mA Output Sink Current
  - 32-mA Output Source Current
- **3-State Outputs**

## description

The 'FCT646T devices consist of a bus transceiver circuit with 3-state, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers as the appropriate

clock pin goes to a high logic level. Output-enable ( $\overline{G}$ ) and direction (DIR) inputs control the transceiver function. In the transceiver mode, data present at the high-impedance port can be stored in either the A or B register, or in both. Select controls (SAB, SBA) can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when G is low. In the isolation mode (G is high), A data can be stored in the B register and/or B data can be stored in the A register.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested
unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

A3	7						2	23
NC	8 [						2	22
$A_4$	9 10 11						2	21
A <sub>5</sub>	10						2	20
A <sub>6</sub>	11						1	19
Ŭ	<b>12</b>	13	14	15	16	17	18	

NC - No internal connection

B

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#### **PIN DESCRIPTION**

NAME	DESCRIPTION
A	Data register A inputs, data register B outputs
В	Data register B inputs, data register A outputs
CPAB, CPBA	Clock-pulse inputs
SAB, SBA	Output data-source-select inputs
DIR, G	Output-enable inputs

## **ORDERING INFORMATION**

TA	PAC	KAGE <sup>†</sup>	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP – Q	Tape and reel	5.4	CY74FCT646CTQCT	FCT646C
	SOIC - SO	Tube	5.4	CY74FCT646CTSOC	FCT646C
	3010 - 30	Tape and reel	5.4	CY74FCT646CTSOCT	FC1046C
	QSOP – Q	Tape and reel	6.3	CY74FCT646ATQCT	FCT646A
–40°C to 85°C	SOIC - SO	Tube	6.3	CY74FCT646ATSOC	FCT646A
	3010 - 30	Tape and reel	6.3	CY74FCT646ATSOCT	FC1040A
	QSOP – Q	Tape and reel	9	CY74FCT646TQCT	FCT646
	SOIC – SO	Tube	9	CY74FCT646TSOC	FCT646
	3010 - 30	Tape and reel	9	CY74FCT646TSOCT	101040
	LCC – L	Tube	6	CY54FCT646CTLMB	
–55°C to 125°C	CDIP – D	Tube	7.7	CY54FCT646ATDMB	
	LCC – L	Tube	7.7	CY54FCT646ATLMB	
	LCC - L	Tube	11	CY54FCT646TLMB	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

		INP	UTS			DATA	a I/o‡	OPERATION
G	DIR	CPAB	СРВА	SAB	SBA	A <sub>1</sub> -A <sub>8</sub>	В <sub>1</sub> –В8	OR FUNCTION
Н	Х	H or L	H or L	Х	Х	Input	Input	Isolation
н	Х	$\uparrow$	$\uparrow$	Х	Х	Input	Input	Store A and B data
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus

H = High logic level, L = Low logic level,  $\uparrow$  = Low-to-high transition, X = Don't care

<sup>‡</sup> The data output functions can be enabled or disabled by various signals at the  $\overline{G}$  or DIR inputs. Data input functions always are enabled, i.e., data at the bus pins is stored on every low-to-high transition of the clock inputs.



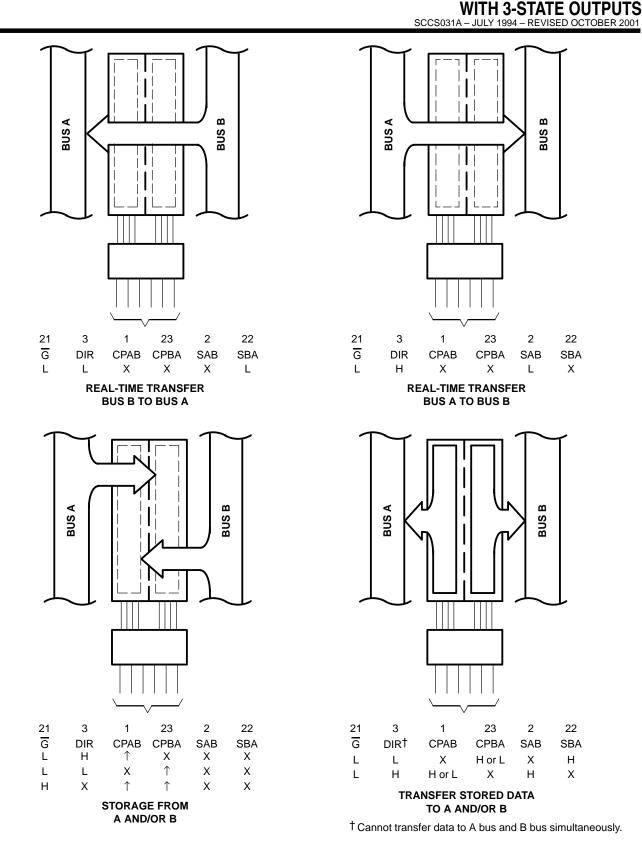


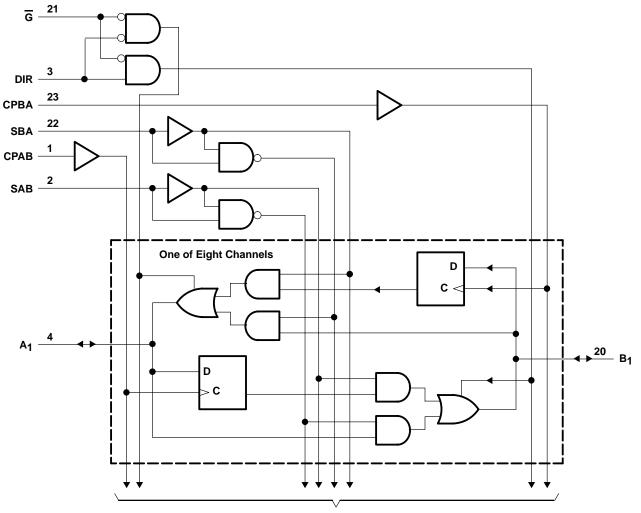
Figure 1. Bus-Management Functions

CY54FCT646T, CY74FCT646T

**8-BIT REGISTERED TRANSCEIVERS** 

## **CY54FCT646T, CY74FCT646T 8-BIT REGISTÉRED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCCS031A - JULY 1994 - REVISED OCTOBER 2001

## logic diagram (positive logic)



**To Seven Other Channels** 

Pin numbers shown are for the Q and SO packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 1): Q package	61°C/W
SO package	46°C/W
Ambient temperature range with power applied, T <sub>A</sub>	–65°C to 135°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



# CY54FCT646T, CY74FCT646T 8-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS SCCS031A – JULY 1994 – REVISED OCTOBER 2001

## recommended operating conditions (see Note 2)

		CY	54FCT64	6T	CY74FCT646T			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			48			64	mA
ТА	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TERT CONDITIONS		CY	54FCT64	46T	CY	74FCT64	6T		
PARAMETER		TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
M	V <sub>CC</sub> = 4.5 V,	I <sub>IN</sub> = -18 mA			-0.7	-1.2				v	
VIK	V <sub>CC</sub> = 4.75 V,	I <sub>IN</sub> = -18 mA						-0.7	-1.2	v	
	V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -12 mA		2.4	3.3						
Vон	V <sub>CC</sub> = 4.75 V	I <sub>OH</sub> = -32 mA					2			V	
	VCC = 4.75 V	I <sub>OH</sub> = -15 mA					2.4	3.3			
Ve	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 48 mA			0.3	0.55				v	
VOL	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 64 mA						0.3	0.55	v	
V <sub>hys</sub>	All inputs				0.2			0.2		V	
1.	V <sub>CC</sub> = 5.5 V,	$V_{IN} = V_{CC}$				5				μA	
łĮ	V <sub>CC</sub> = 5.25 V,	$V_{IN} = V_{CC}$							5	μA	
I	V <sub>CC</sub> = 5.5 V,	V <sub>IN</sub> = 2.7 V				±1				μA	
ΙΗ	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 2.7 V							±1	μА	
1	V <sub>CC</sub> = 5.5 V,	V <sub>IN</sub> = 0.5 V				±1				μA	
hΓ	V <sub>CC</sub> = 5.25 V,	V <sub>IN</sub> = 0.5 V							±1	μΑ	
	V <sub>CC</sub> = 5.5 V,	V <sub>OUT</sub> = 2.7 V				10				μA	
IOZH	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 2.7 V							10	μι	
107	V <sub>CC</sub> = 5.5 V, V <sub>OUT</sub> = 0.5 V					-10				μA	
IOZL	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0.5 V							-10	μΑ	
los‡	V <sub>CC</sub> = 5.5 V,	V <sub>OUT</sub> = 0 V		-60	-120	-225				mA	
105+	V <sub>CC</sub> = 5.25 V,	V <sub>OUT</sub> = 0 V					-60	-120	-225	111/-	
l <sub>off</sub>	$V_{CC} = 0 V,$	V <sub>OUT</sub> = 4.5 V				±1			±1	μA	
	V <sub>CC</sub> = 5.5 V,	$V_{IN} \leq 0.2 V$ ,	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				mA	
ICC	V <sub>CC</sub> = 5.25 V,	$V_{IN} \le 0.2 V$ ,	$V_{IN} \ge V_{CC} - 0.2 V$					0.1	0.2	111/7	
	$V_{CC}$ = 5.5 V, $V_{IN}$ =	3.4 V§, f <sub>1</sub> = 0, Outpu	ts open		0.5	2					
∆ICC	V <sub>CC</sub> = 5.25 V, V <sub>IN</sub> :	= 3.4 V§, f <sub>1</sub> = 0, Outp	uts open					0.5	2	mA	
1¶	$V_{CC} = 5.5 \text{ V}$ , One input switching at 50% duty cycle, Outputs open, $\overline{G} = DIR = GND$ , SAB = $\overline{SBA} = GND$ , $V_{IN} \le 0.2 \text{ V}$ or $V_{IN} \ge V_{CC} - 0.2 \text{ V}$				0.06	0.12				mA	
ICCD <sup>¶</sup>		input switching at 5 <u>0</u> 9 DIR = GND, SAB = SI ≥ V <sub>CC</sub> – 0.2 V						0.06	0.12	MH	

<sup>†</sup> Typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ .

<sup>‡</sup> Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input ( $V_{IN}$  = 3.4 V); all other inputs at V<sub>CC</sub> or GND

¶ This parameter is derived for use in total power-supply calculations.



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

				CY	54FCT6	46T	CY	74FCT64	16T	
PARAMETER		EST CONDITION	5	MIN	түр†	MAX	MIN	түр†	MAX	UNIT
		One bit switching at f <sub>1</sub> = 5 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$		0.7	1.4				
	$V_{CC} = 5.5 V,$ $f_0 = 10 MHz,$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1.2	3.4				mA
	Outputs open, $\overline{G} = DIR = GND$ , SAB = $\overline{SBA} = GND$	Eight bits switching at f <sub>1</sub> = 5 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$		2.8	5.6ll				IIIA
'c#		at 50% duty cycle	$V_{IN} = 3.4 V \text{ or GND}$		5.1	14.6				
IC."	$V_{CC} = 5.25 V,$ $f_0 = 10 MHz,$ Outputs open, $\overline{G} = DIR = GND,$ SAB = SBA = GND	One bit switching at f <sub>1</sub> = 5 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$					0.7	1.4	
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1.2	3.4	mA
		Eight bits switching at f <sub>1</sub> = 5 MHz	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array}$					2.8	5.6ll	IIIA
		at 50% duty cycle	$V_{IN}$ = 3.4 V or GND					5.1	14.6	
Ci					6	10		6	10	pF
Co					8	12		8	12	pF

 $# I_{C} = I_{CC} + \Delta I_{CC} \times D_{H} \times N_{T} + I_{CCD}(f_{0}/2 + f_{1} \times N_{1})$ 

Where:

IC = Total supply current

ICC = Power-supply current with CMOS input levels

 $\Delta I_{CC}$  = Power-supply current for a TTL high input (VIN = 3.4 V)

D<sub>H</sub> = Duty cycle for TTL inputs high

 $N_T$  = Number of TTL inputs at  $D_H$ 

I<sub>CCD</sub> = Dynamic current caused by an input transition pair (HLH or LHL)

 $f_0$  = Clock frequency for registered devices, otherwise zero

f<sub>1</sub> = Input signal frequency

 $N_1$  = Number of inputs changing at  $f_1$ 

All currents are in milliamperes and all frequencies are in megahertz.

Il Values for these conditions are examples of the I<sub>CC</sub> formula.



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## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		CY54FC	CT646T	CY54FC1	646AT	CY54FCT	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration	6		5		5		ns
t <sub>su</sub>	Setup time, data before CPAB↑ or CPBA↑	4.5		2		2		ns
th	Hold time, data after CPAB $\uparrow$ or CPBA $\uparrow$	2		1.5		1.5		ns

## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		CY74FCT646T		CY74FC	Г646AT	CY74FCT	646CT	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration	6		5		5		ns
t <sub>su</sub>	Setup time, data before CPAB $\uparrow$ or CPBA $\uparrow$	4		2		2		ns
t <sub>h</sub>	Hold time, data after CPAB $\uparrow$ or CPBA $\uparrow$	2		1.5		1.5		ns

## switching characteristics over operating free-air temperature range (see Figure 2)

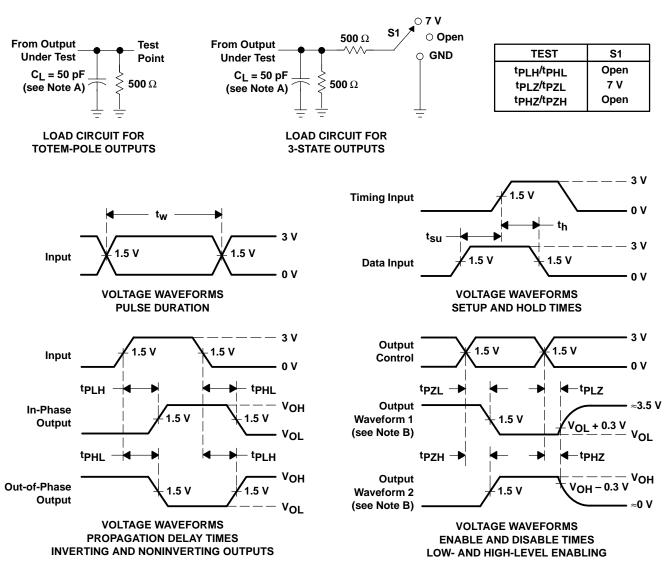
PARAMETER	FROM	то	CY54FC	CT646T	CY54FC	F646AT	CY54FC1	646CT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A or B	B or A	2	11	2	7.7	1.5	6	
<sup>t</sup> PHL		BOLA	2	11	2	7.7	1.5	6	ns
<sup>t</sup> PZH	DIR	A or B	2	15	2	10.5	1.5	8.9	ns
<sup>t</sup> PZL		AUB	2	15	2	10.5	1.5	8.9	115
<sup>t</sup> PHZ	$\overline{G}$ and DIR	A or B	2	11	2	7.7	1.5	7.7	ns
<sup>t</sup> PLZ	G and DIR	AUD	2	11	2	7.7	1.5	7.7	115
<sup>t</sup> PLH	CPAB or CPBA	A or B	2	10	2	7	1.5	6.3	ns
<sup>t</sup> PHL	CFAB OF CFBA	AUB	2	10	2	7	1.5	6.3	115
<sup>t</sup> PLH	SBA or SAB	A or B	2	12	2	8.4	1.5	7	20
<sup>t</sup> PHL	SBA UI SAB	AUB	2	12	2	8.4	1.5	7	ns

## switching characteristics over operating free-air temperature range (see Figure 2)

PARAMETER	FROM	то	CY74FC	CY74FCT646T		Г646AT	CY74FCT646CT		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	A or B	B or A	1.5	9	1.5	6.3	1.5	5.4	20
<sup>t</sup> PHL	AUB	D OF A	1.5	9	1.5	6.3	1.5	5.4	ns
<sup>t</sup> PZH	DIR	A or B	1.5	14	1.5	9.8	1.5	7.8	
<sup>t</sup> PZL	DIK	AUB	1.5	14	1.5	9.8	1.5	7.8	ns
<sup>t</sup> PHZ		and DIR A or B	1.5	9	1.5	6.3	1.5	6.3	ns
<sup>t</sup> PLZ	G and DIR		1.5	9	1.5	6.3	1.5	6.3	115
<sup>t</sup> PLH		CPAB or CPBA A or B	1.5	9	1.5	6.3	1.5	5.7	
<sup>t</sup> PHL			1.5	9	1.5	6.3	1.5	5.7	ns
<sup>t</sup> PLH	SBA or SAB	AB A or B	1.5	11	1.5	7.7	1.5	6.2	
<sup>t</sup> PHL	SBA UI SAB	AUB	1.5	11	1.5	7.7	1.5	6.2	ns



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## PARAMETER MEASUREMENT INFORMATION

NOTES: A. C<sub>1</sub> includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





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28-Aug-2010

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-9222301M3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9222303M3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
5962-9222303MLA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	Purchase Samples
5962-9222305M3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
CY54FCT646ATDMB	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	Purchase Samples
CY54FCT646ATLMB	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
CY54FCT646CTLMB	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	Purchase Samples
CY74FCT646ATQCT	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646ATQCTE4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646ATQCTG4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646ATSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646ATSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646ATSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646ATSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CY74FCT646ATSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CY74FCT646ATSOCTG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CY74FCT646CTQCT	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646CTQCTE4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646CTQCTG4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	Purchase Samples
CY74FCT646CTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
CY74FCT646CTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646CTSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646CTSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646CTSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646CTSOCTG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOCG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT646TSOCTG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.



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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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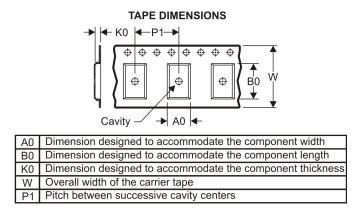
## PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT646ATQCT	SSOP/ QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT646ATSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT646CTQCT	SSOP/ QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT646CTSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT646TSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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## PACKAGE MATERIALS INFORMATION

23-Jul-2010



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT646ATQCT	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0
CY74FCT646ATSOCT	SOIC	DW	24	2000	346.0	346.0	41.0
CY74FCT646CTQCT	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0
CY74FCT646CTSOCT	SOIC	DW	24	2000	346.0	346.0	41.0
CY74FCT646TSOCT	SOIC	DW	24	2000	346.0	346.0	41.0

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